IPC ASSOCIATION ELECTRONIC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				s Materials	ials and Mfg Information			
Supplier	r Information														
Company name* Cor				Company unique ID			Unique ID Authority				R	Response Date*			
nsemi											20	2025-09-14			
Contact N	ame	Title - Contact			F	Phone - Contact*				E	Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance			1	NA				P	Product-Env-Stewards@onsemi.com			
uthorize	d Representative*	Title - Representative			F	Phone - Representative*				E	Email - Representative*				
Product-I	Env-Stewards	Product Enviro Compliance			]	NA				P	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date   Version   Manufacturing Si		Site	Weight*	UOM	Unit Type			
		NB6L295MMNTXG CML DUAL PRO		G DELAY		2025-09-14	MY1			44.91	mg	Each			
<b>Ianufa</b>	cturing Proccess Inform	ation										·			
	Terminal Plating / Grid Array M	Terminal Base Alloy J-STD-020		-STD-020 MSL	Rating	Peak Process Body Temperatur		Max Time	at Peak Ter	mperature Nu	umber of Reflow Cy	cles			
Matte Tin (Sn) - annealed		CU Alloy 1			260 C 30			seconds 3							
omments	<b>i</b>														
vel 1 - m	aximum time at peak tempera	ture during so	ldering is 10-3	30 seconds											
or more	information regarding materia	al composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier pr											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.98	mg	Supplier	Silicon (Si)	7440-21-3		2.98	mg
Die Attach	0.55	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.11	mg
			Supplier	Silver (Ag)	7440-22-4		0.44	mg
Lead Frame	16.85		Supplier	Silver (Ag)	7440-22-4		0.1685	mg
			Supplier	Tin (Sn)	7440-31-5		0.0421	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0371	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0421	mg
			Supplier	Copper (Cu)	7440-50-8		16.5602	mg
Mold Compound-Black	22.31		Supplier	Epoxy and Phenolic Resin	40216-08-8		1.7848	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1115	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.4462	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		19.2981	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6693	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5		0.33	mg